

PHILIPS

sense **and** simplicity

The Multiphysics Approach: The Electrochemical Machining Process

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Advanced Technology Center

November, 2008

Outline

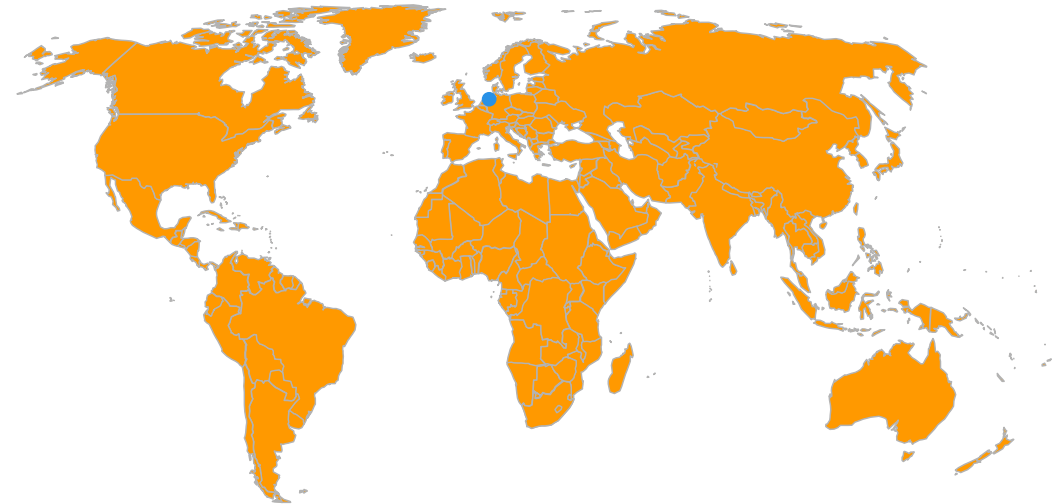
- Introduction
- ECM Process description
- Validation
- Application
- Conclusion



Royal Philips Electronics

- Founded in 1891
- Headquarters: Amsterdam, The Netherlands
- One of the largest global diversified industrial company with sales in 2007 of EUR 26,793 million
- A multinational workforce of 133,000 employees (April 2008)
- An R&D force with expenditures of EUR 1,629 million (2007)

Globally present with manufacturing sites in 28 countries and sales outlets in 150 countries



A global presence

Design, development and assembly centers throughout the world



2007 results: Consumer Lifestyle*

- Focused on innovative lifestyle solutions for personal wellbeing
- Many leading market positions
- Contributing to the Philips brand
- Strong marketing and sales capabilities
- Consumer-driven insights and dedicated business models driving innovation and differentiation
- Entering strategic new value spaces
- Driving sustainable, profitable growth



Active Crystals



Portable Media devices

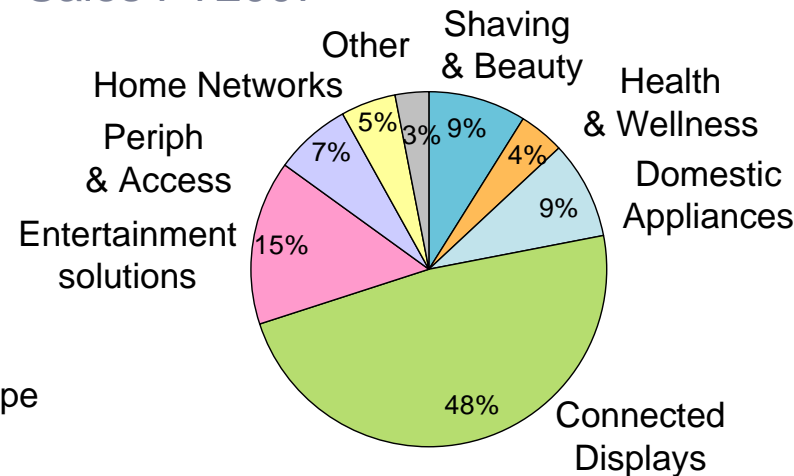
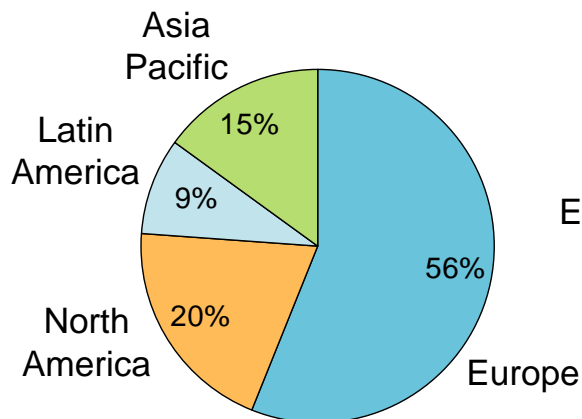


Arcitec



Flexicare

Sales FY2007



*Results given are based on 2007 results reported by the Consumer Electronics and DAP divisions prior to their merger into the Consumer Lifestyle sector on January 1, 2008

Making a difference

The Consumer Lifestyle businesses

Television



Shaving & Beauty



Domestic Appliances



Audio Video & Multimedia



Peripherals & Accessories

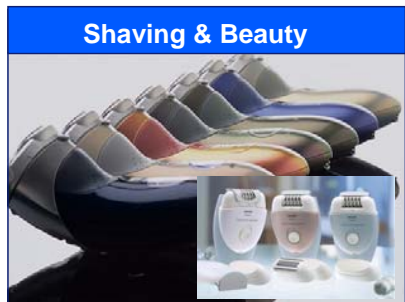
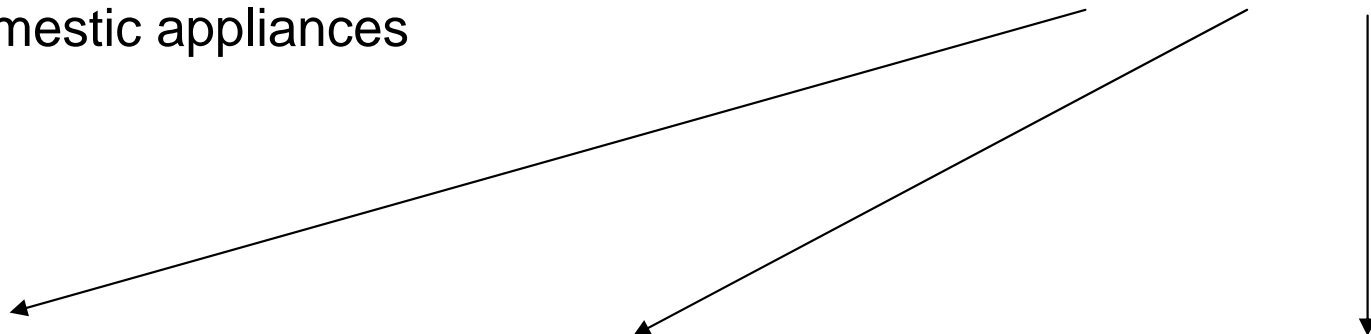


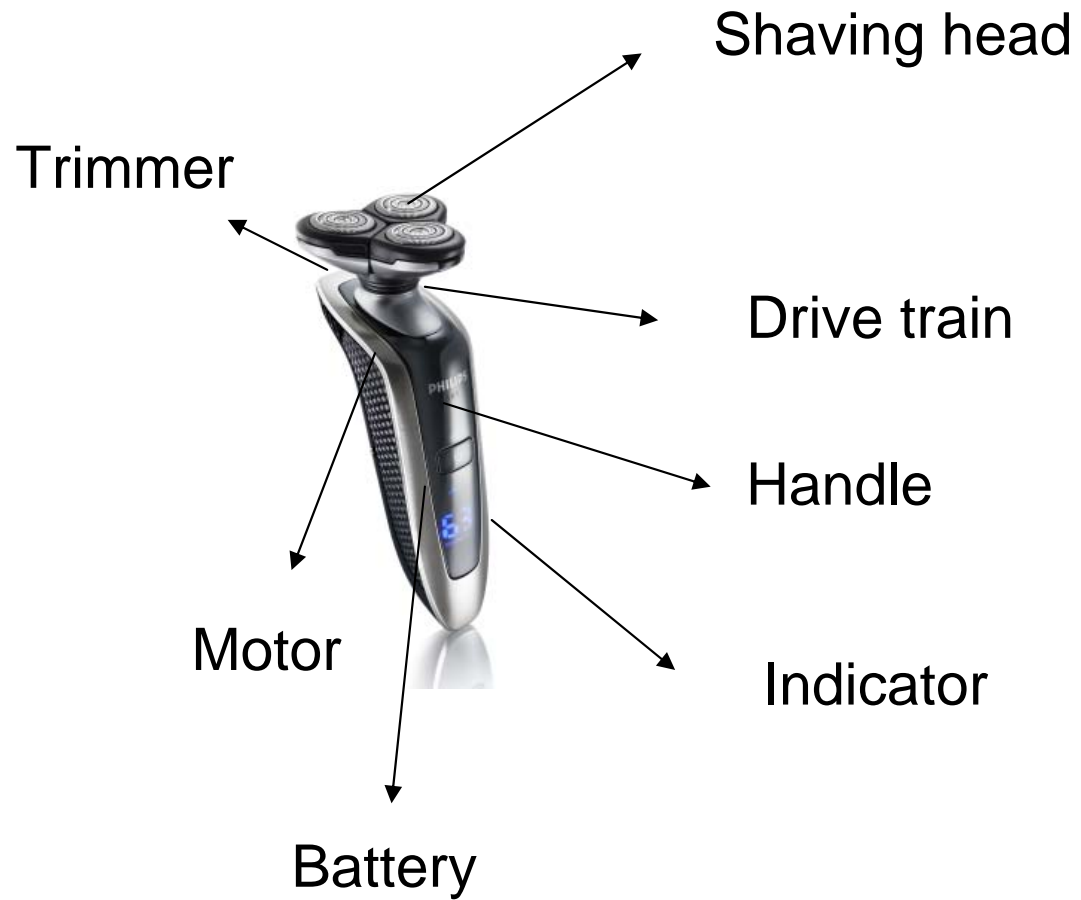
Health & Wellness



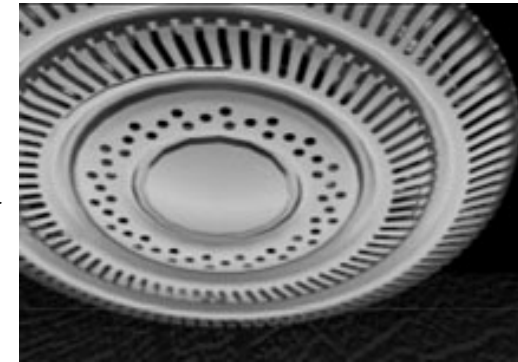
ATC, Advanced Technology Center

- ATC is CL' technology center serving all Lines of Business
- 110 employees (90% PhD, MSc and BSc)
- Our key success factor is our in-depth understanding of CL applications focussing on domestic appliances

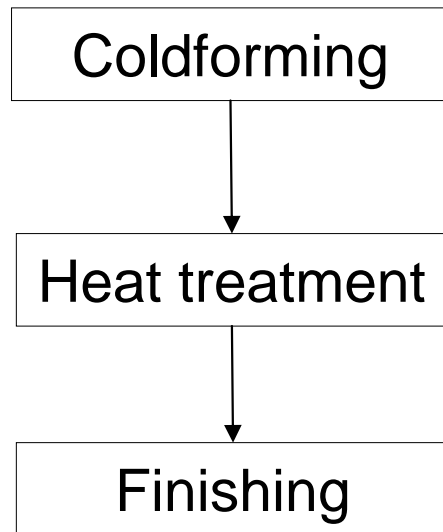




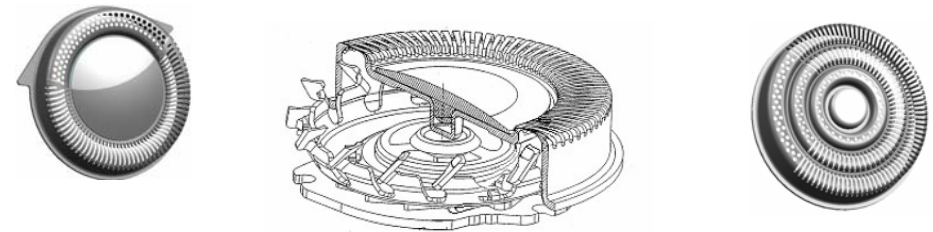
Cap



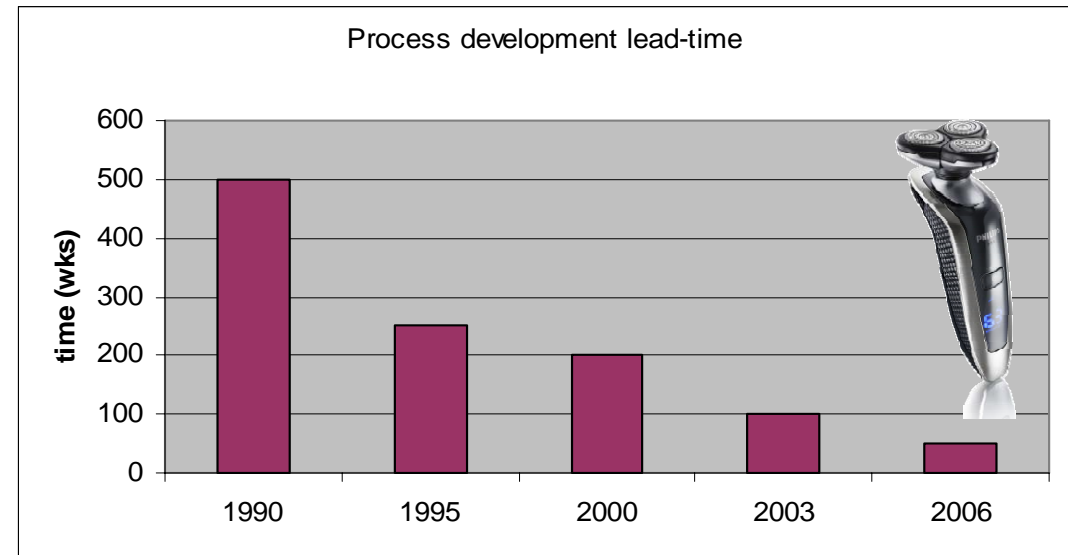
Shaving cap production process



More complex shape



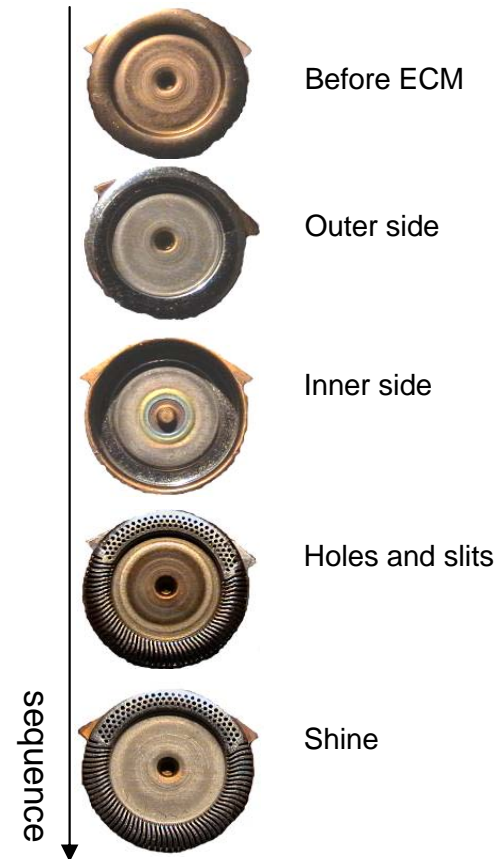
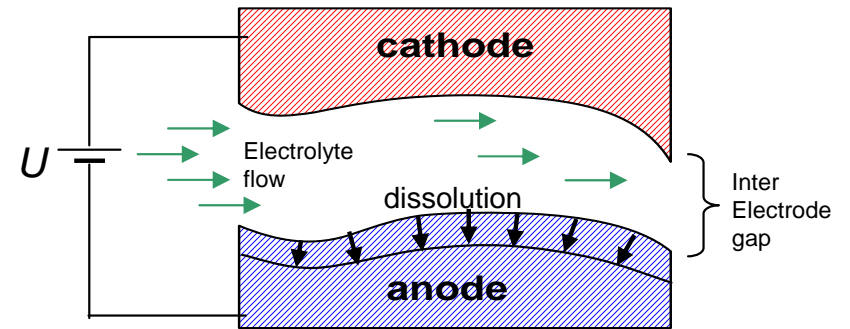
Shorter time to market



Cold forming



Finishing (ECM)



Business objectives

We are constantly seeking opportunities to:

- Enhance shaving performance
- Increase profitability
- Improve process robustness & predictability

Product accuracy

**Investments and
process cost**

**Cost of Non
Quality**

Approach

- To simulate the ECM process
 - *ECM is not a black box process !*
 - *Process simulation to be used upfront experiment to get process settings much closer to these optimal for given result.*
 - *Simulation results depends on the model used; it can greatly support and minimize experimental effort but cannot eliminate real-time experiments.*

5 Desired states

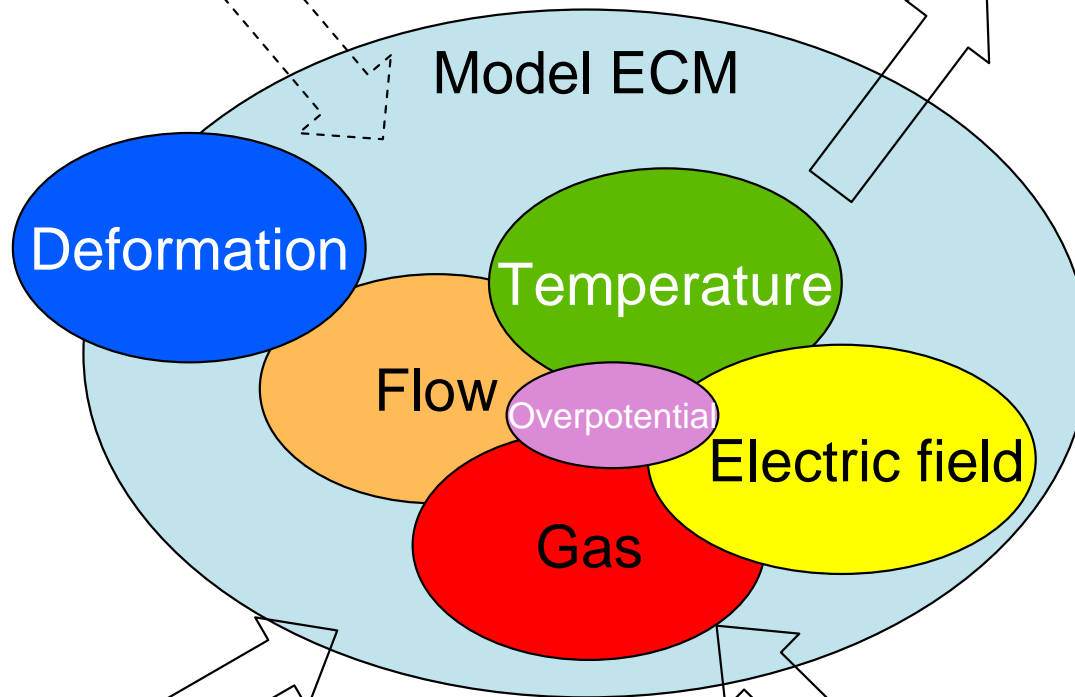
- Process development time is decreased
- Development cost is minimized
- Experiments run mainly virtually (are simulated)
- Real experiment goes 'first time right' after simulation
- Simulated process is robust and accuracy fulfills specification requirements



Inventory of process governing principles

Process disturbances (!)
e.g. support misalignment

Process outputs:
Shape



Process parameters:

- Voltage
- Electrolyte concentration
- Flow pressure
- Inter electrode gap
- ...

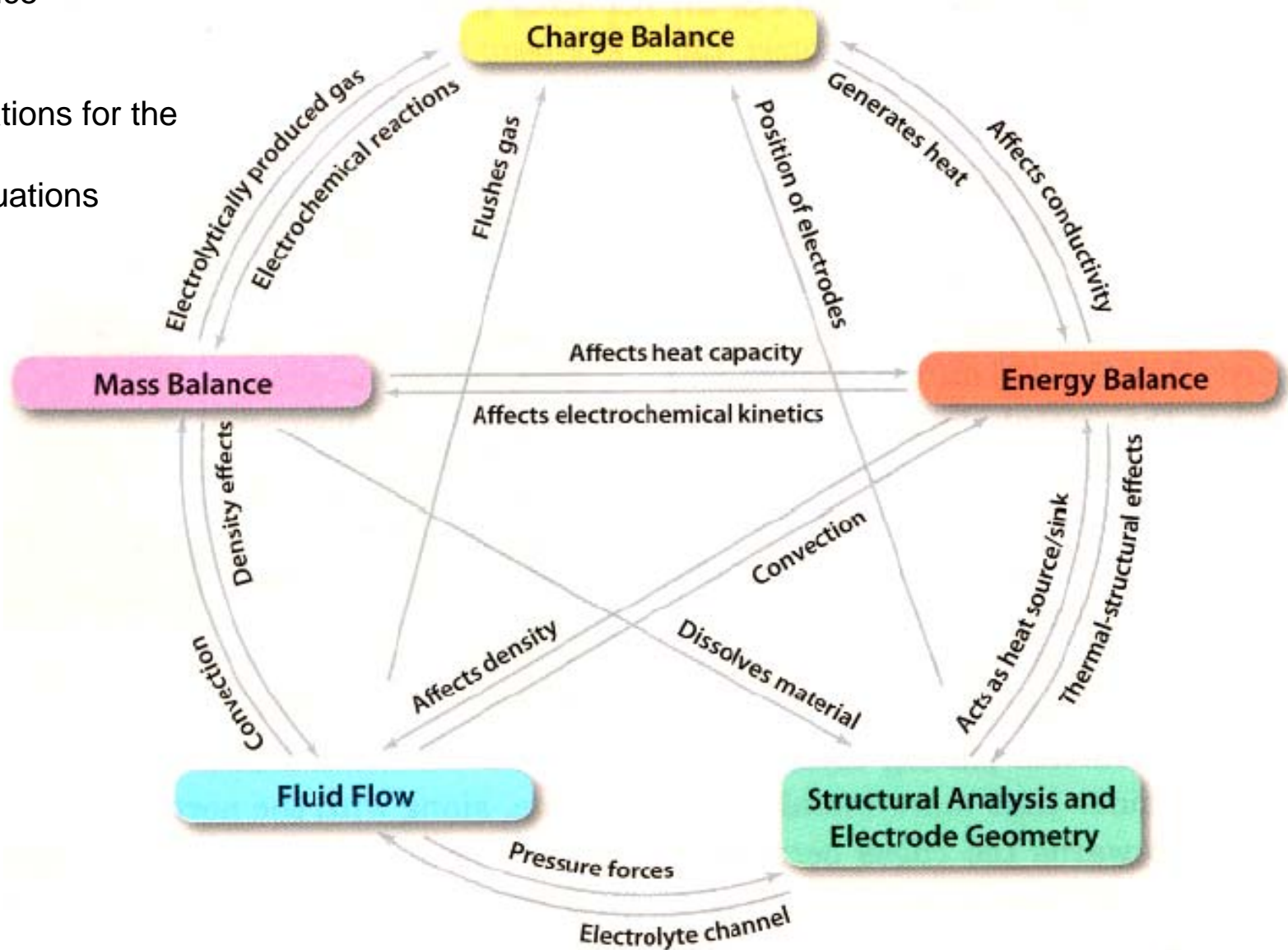
Input:
product shape

- **Faraday's law** driven dissolution
- **Navier-Stokes** description of electrolyte flow conditions (also for compressible non-Newtonian liquid) in laminar & turbulent domain
- **Ohm's Law** and distribution of electric field
- **Joule-Lentz** heat generated during dissolution increasing electrolyte conductivity
- Oxygen & hydrogen **gas evolution** altering flow conditions and decreasing conductivity
- **Overpotential** of cathode & anode
- **Current efficiency** dependency
- Possible elastic **deformation** of the typically fragile (thin wall) product due to electrolyte pressure

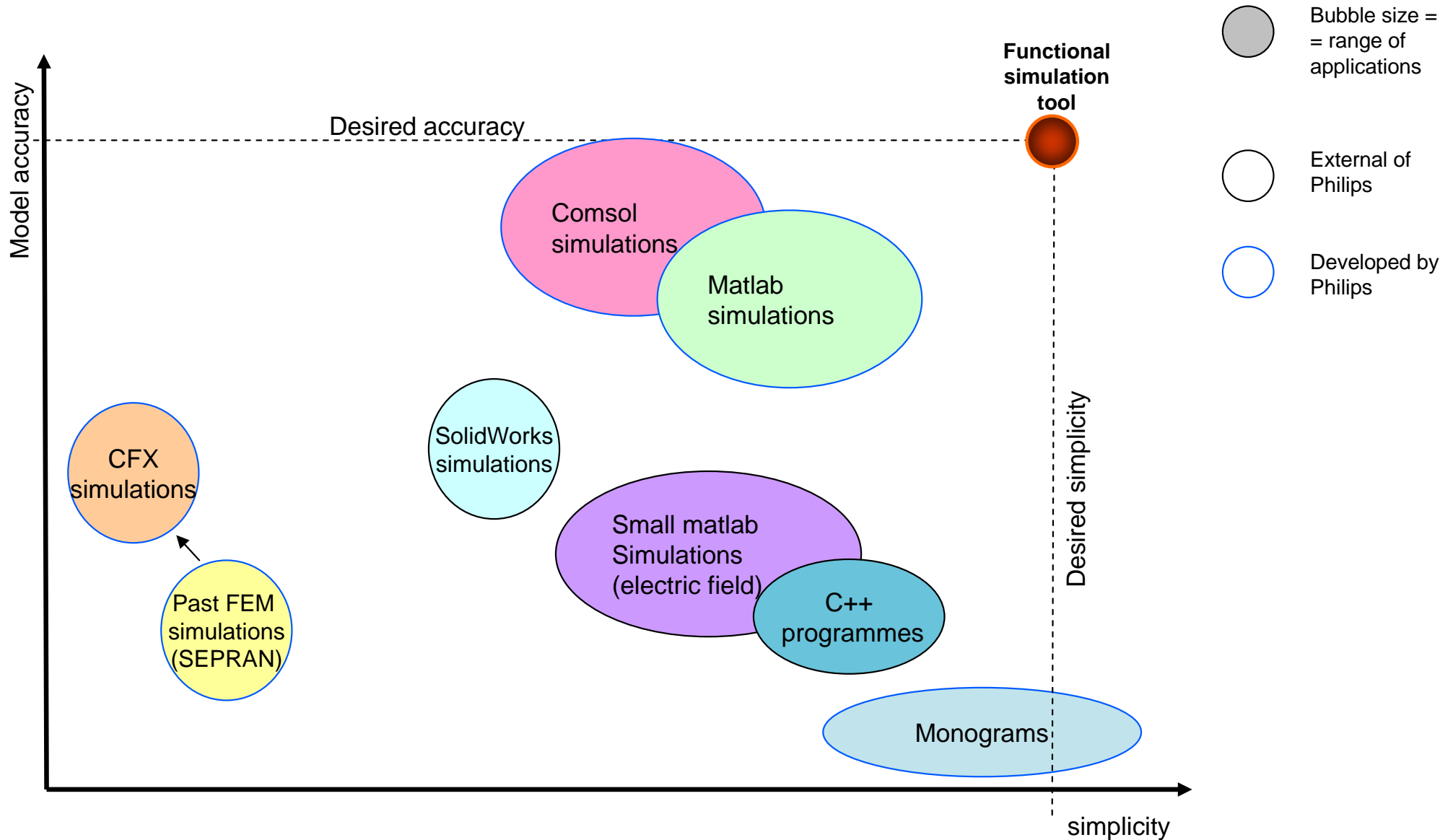
Multiphysics high level problem description

ECM model “by balance”

- Mass balance equations for the process gap
- Energy balance equations

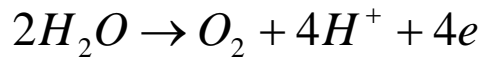
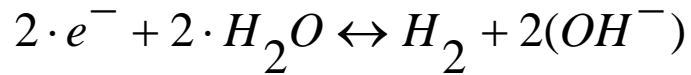
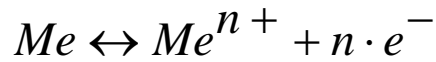


ECM modelling map – internal / external Philips



Material dissolution

- Reactions (selection):



- Material dissolution:

$$v_n = K \cdot \eta(J) \cdot J \text{ [m/s]}$$

- Efficiency $\eta(J)$:

$$\Delta m_{\text{theory}} = \frac{M \cdot I}{z \cdot F} \cdot \Delta t$$

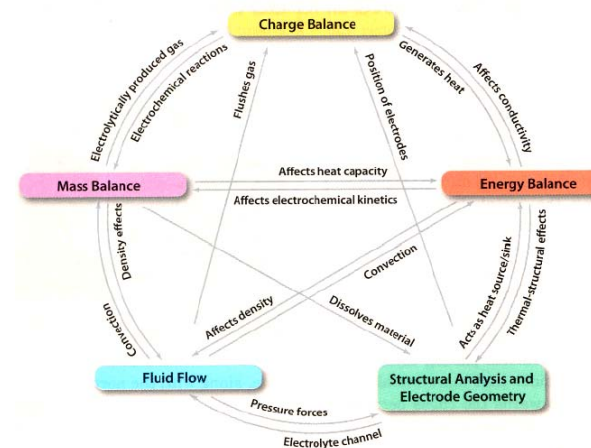
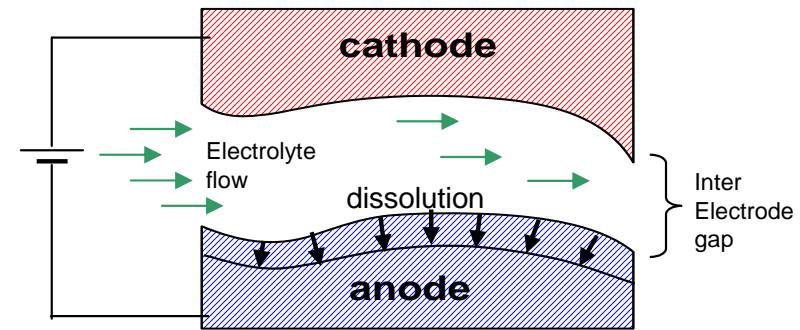
$$\eta(J) = \frac{\Delta m_{\text{experimental}}}{\Delta m_{\text{theory}}} = c_1 + \frac{2}{\pi} (c_2 - c_1) \cdot \text{atan}(c_3(J - c_4)) \text{ [%]}$$

where:

J current density

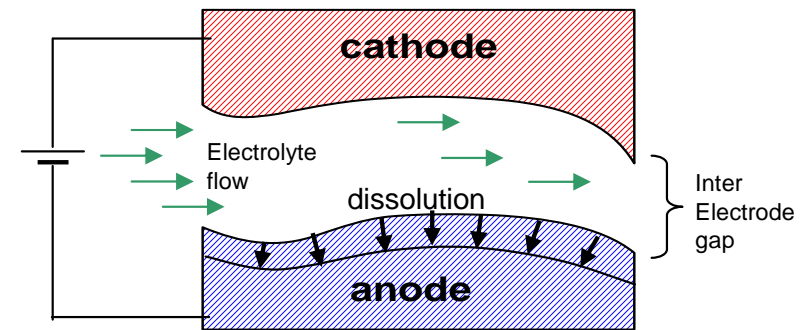
K electrochemical constant

c_1, c_2, c_3, c_4 process constants



Conductivity

- Temperature (T)
 - Joule’s heating
 - Conduction
 - Convection
- Gas concentration (C)
 - Flux at the surface
 - Diffusion
 - Convection

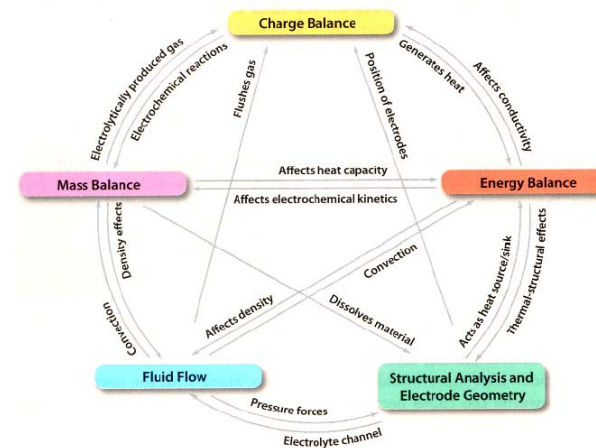


Conductivity:

$$\frac{1}{\sigma} = \rho_0 (1 + volfrac)^{bp} \cdot (1 + \alpha(T - T_0)) \text{ [m/S]}$$

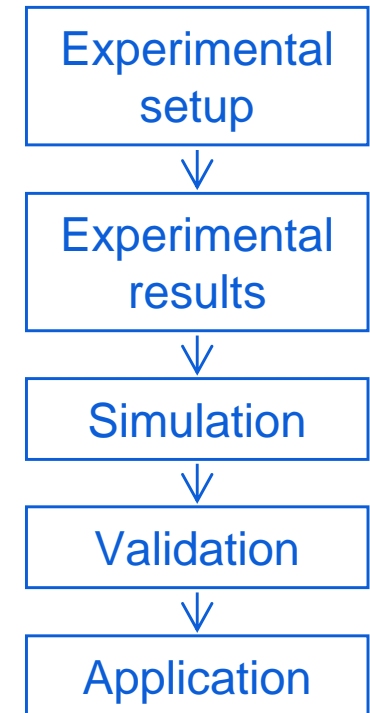
Where the gas volume fraction is:

$$volfrac = \frac{C}{C + M_{el}} \text{ [-]}$$



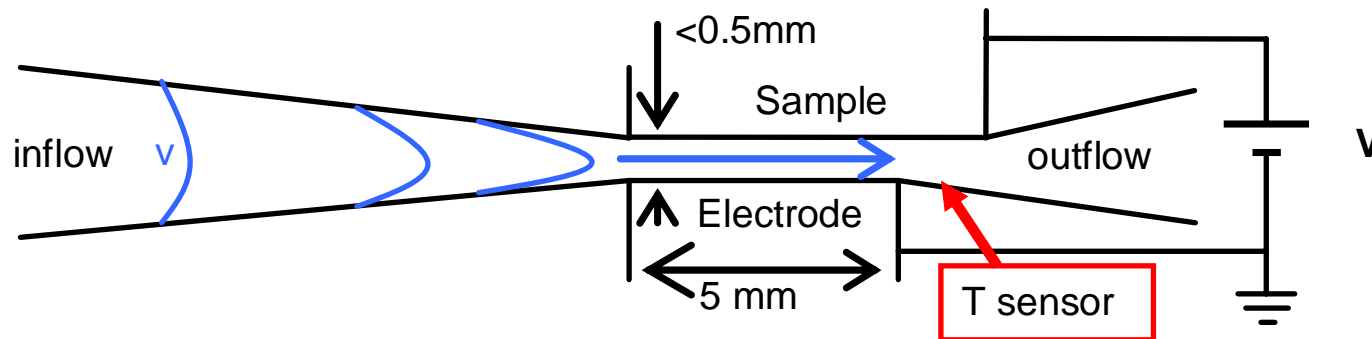
Multiphysics model validation case

- Variables:
 - Inlet temperature (10, 25 and 40 °C)
 - Solution concentration (50, 130 and 230 g/l)
- Outcome:
 - Material removal efficiency to determine:
$$\eta(J) = c_1 + \frac{2}{\pi}(c_2 - c_1) \cdot \text{atan}(c_3(J - c_4)) [\%]$$

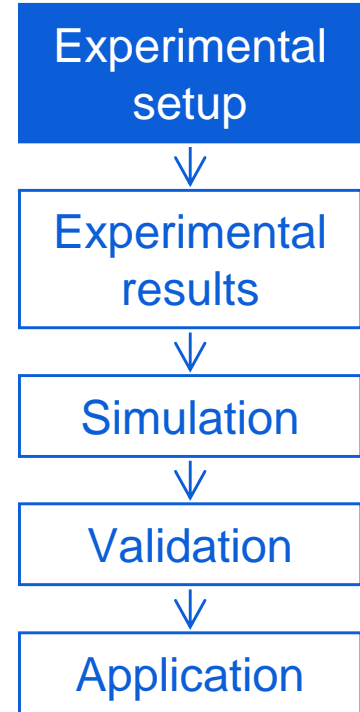
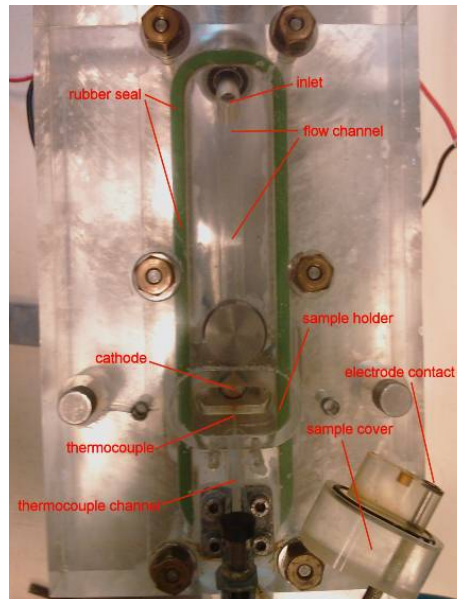


Experimental setup

Schematic of the lab scale process:



Experimental setup (top view):



Experimental results

Material dissolution speed:

$$v_n = K \cdot \eta(J) \cdot J \text{ [m/s]}$$

Efficiency:

$$\eta(J) = \frac{\Delta m_{\text{experimental}}}{\Delta m_{\text{theory}}} = c_1 + \frac{2}{\pi} (c_2 - c_1) \cdot \text{atan}(c_3(J - c_4)) \text{ [%]}$$

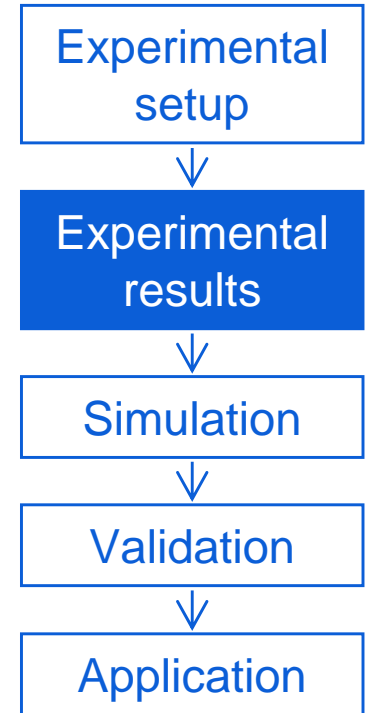
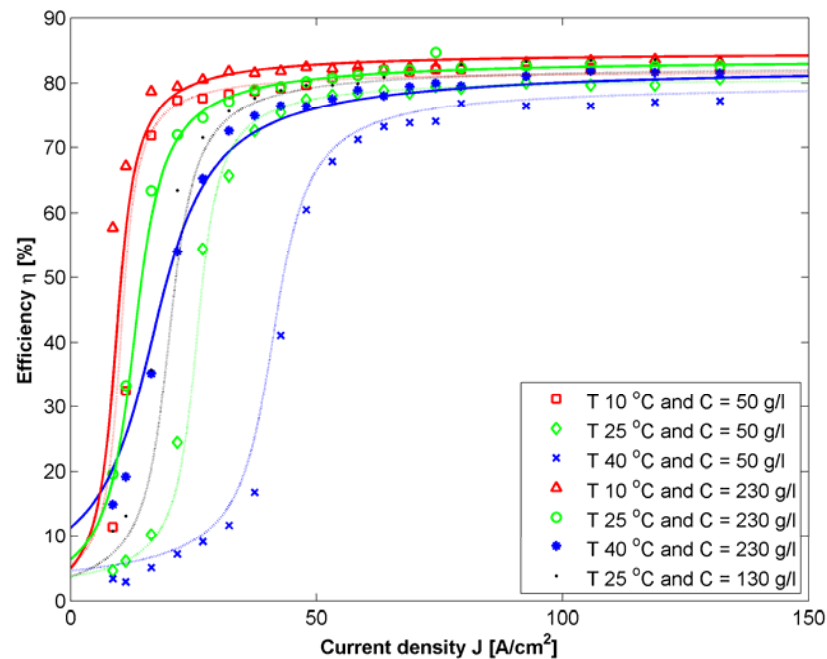
Best fit:

$$c_1 = 40.7$$

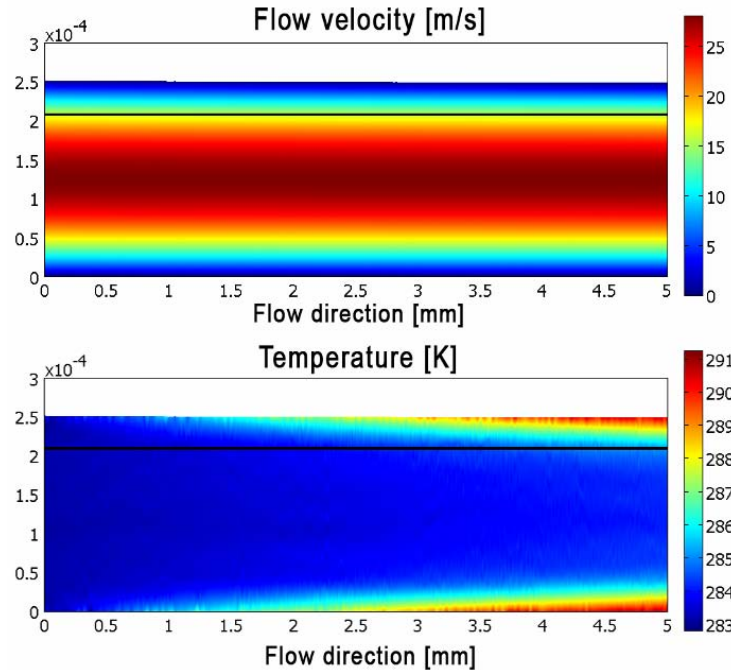
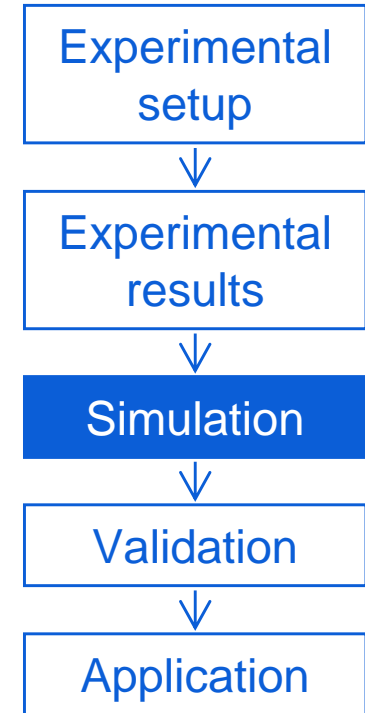
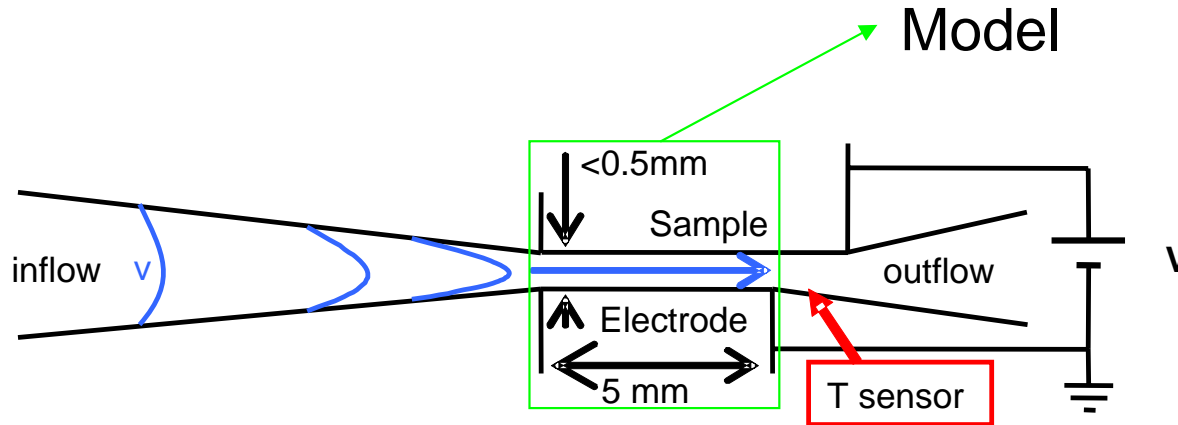
$$c_2 = 75.4 - 0.0676 \cdot T + 1.86 \cdot \ln(C)$$

$$c_3 = 0.684 - 0.00772 \cdot T - 0.0475 \cdot \ln(C)$$

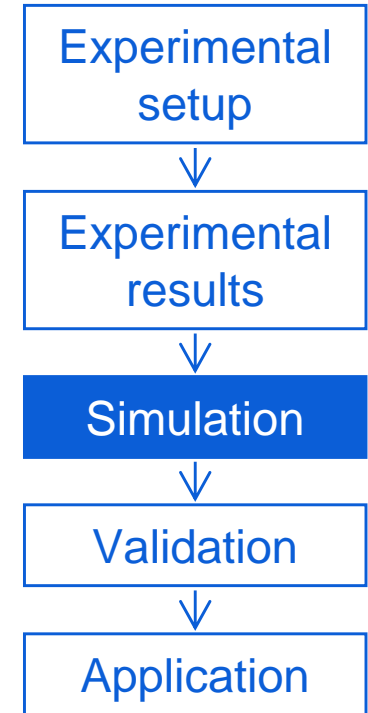
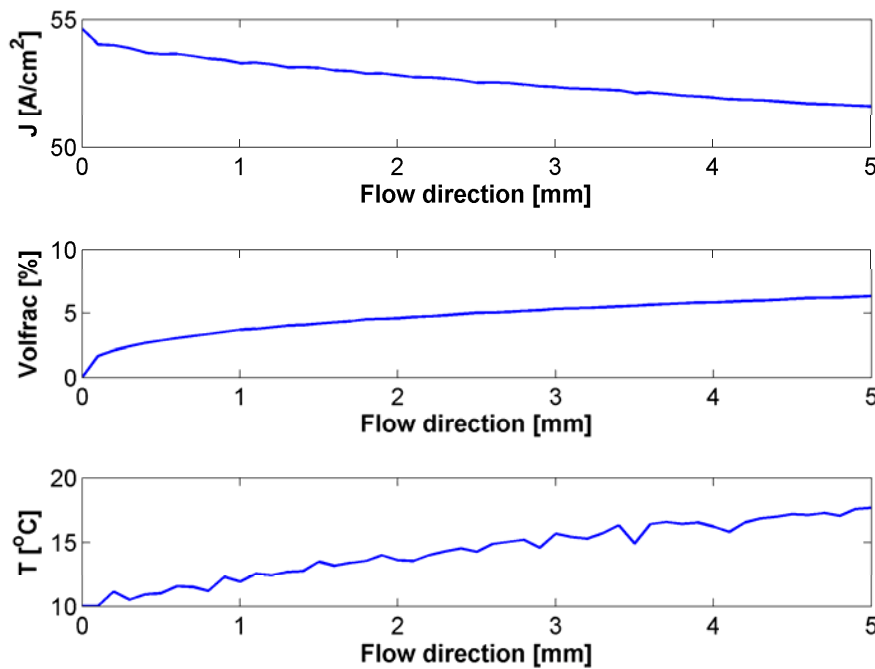
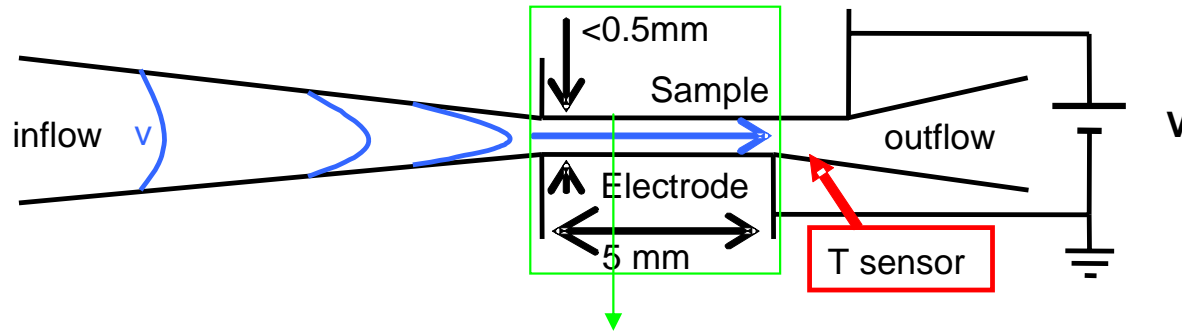
$$c_4 = -2.05 + 1.25 \cdot T + 0.0387 \cdot C - 0.00437 \cdot C \cdot T$$



COMSOL multiphysics model

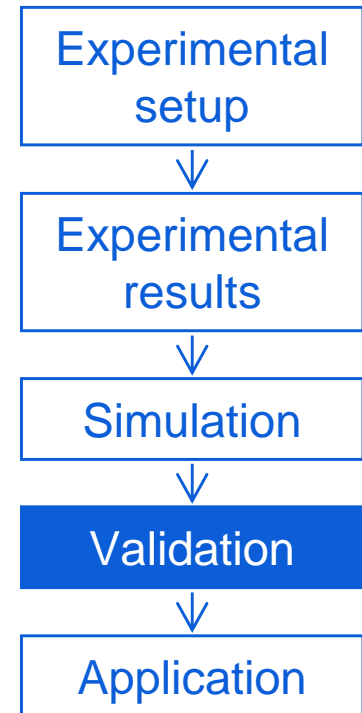
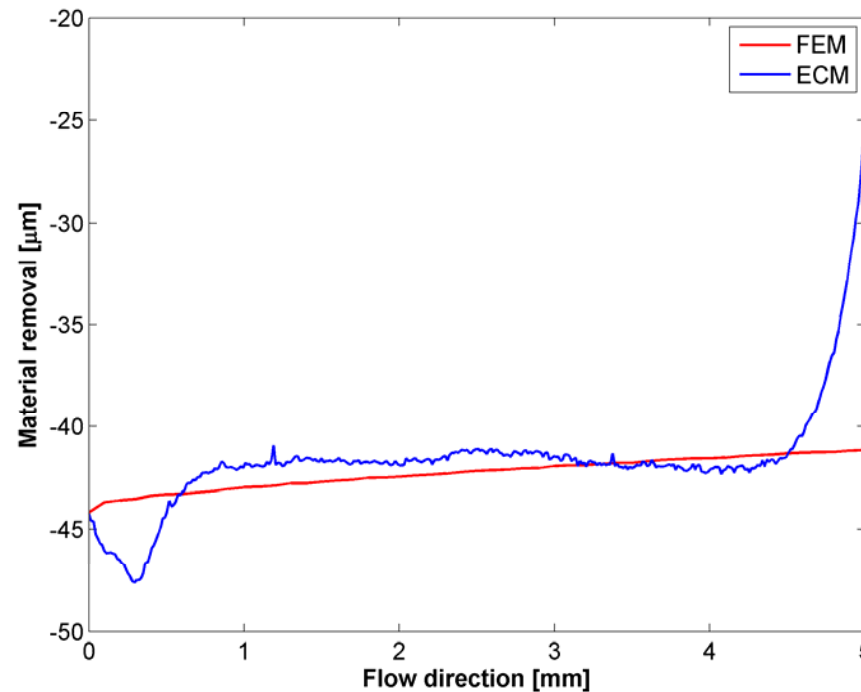


Comsol multiphysics model: process variables

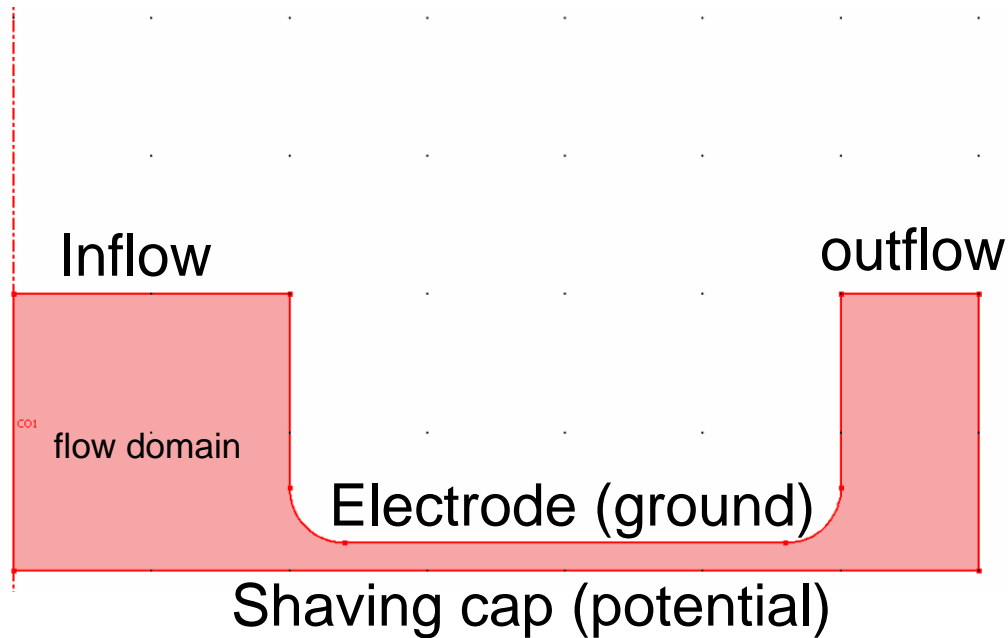


Validation of material removal

- Comparison of profile measurements and simulations



Example: creating a cavity in a shaving cap



Mesh:



Simulation:

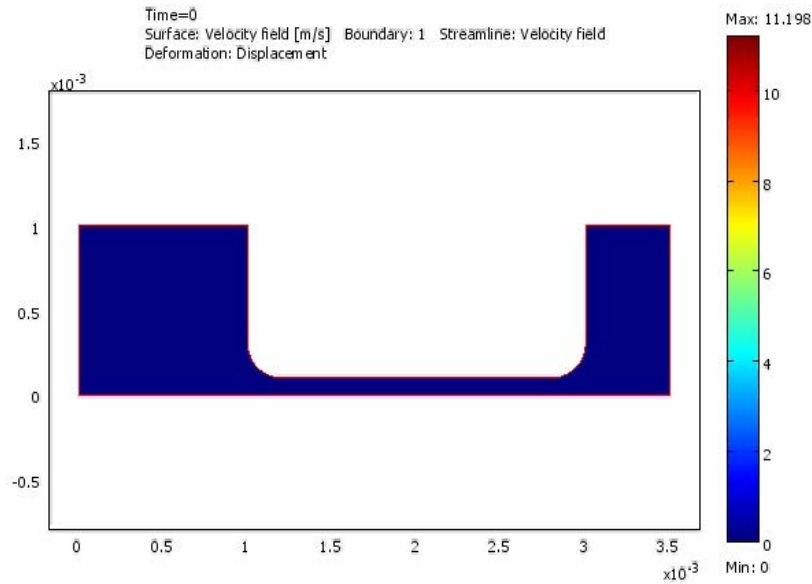
- Coupled physics (axial symmetric):

- Navier-stokes (u,v)
- Potential (V)
- Convection/diffusion (C)
- Convection/conduction (T)
- Moving mesh (r,z)

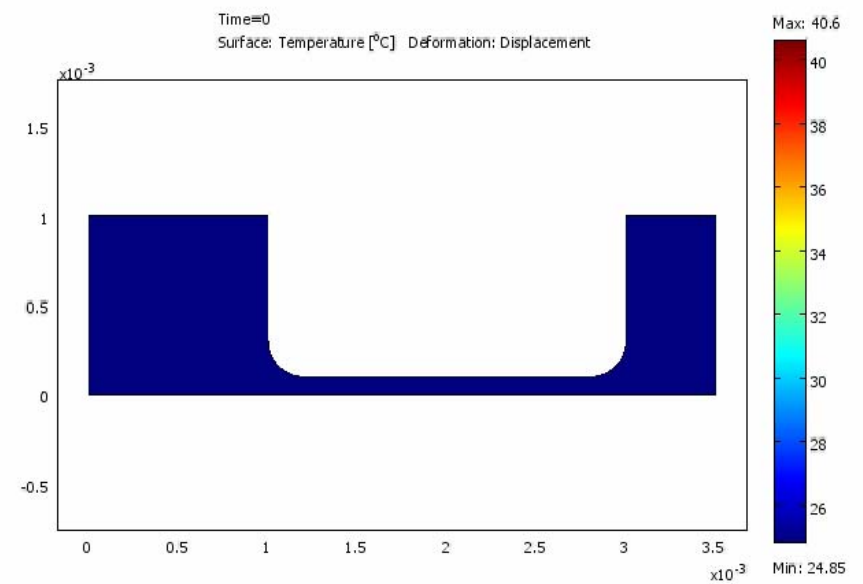
-Time: 0 to 10 seconds

- Feed rate: 25 $\mu\text{m/s}$

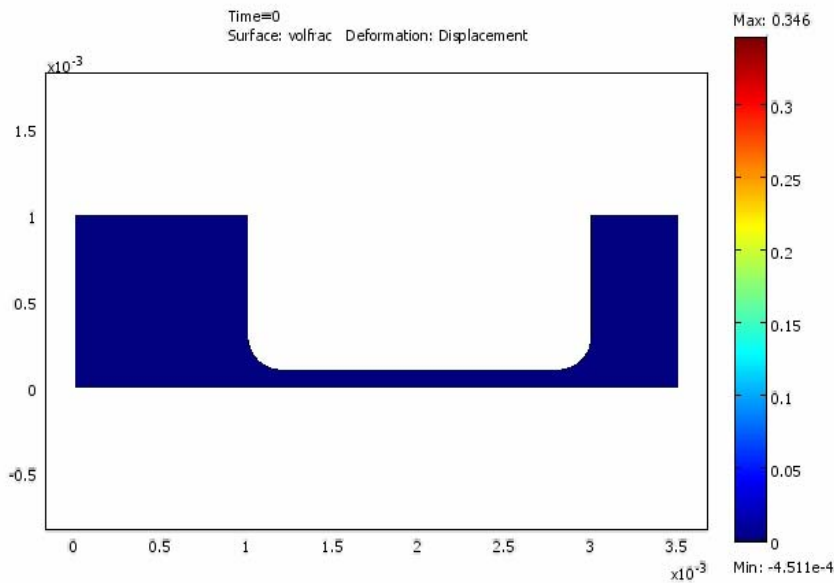
Flow velocity [m/s]



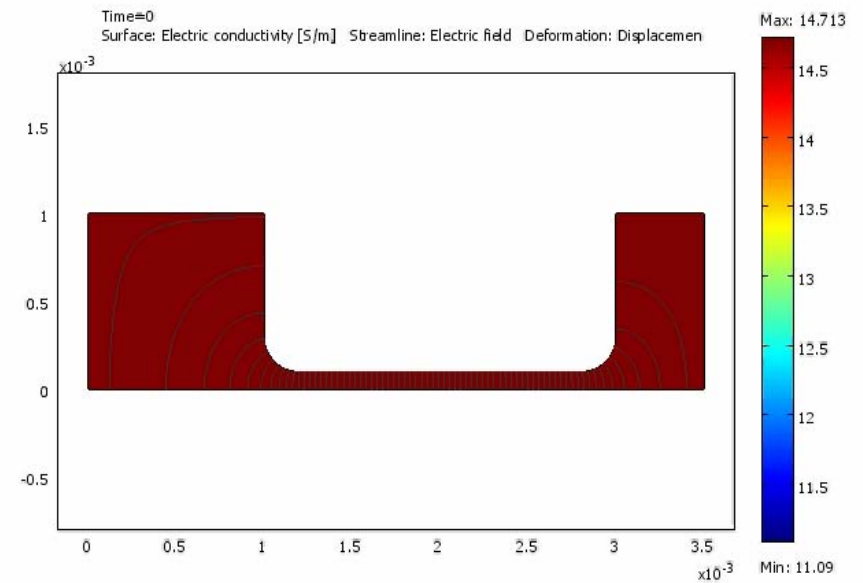
Temperature [K]



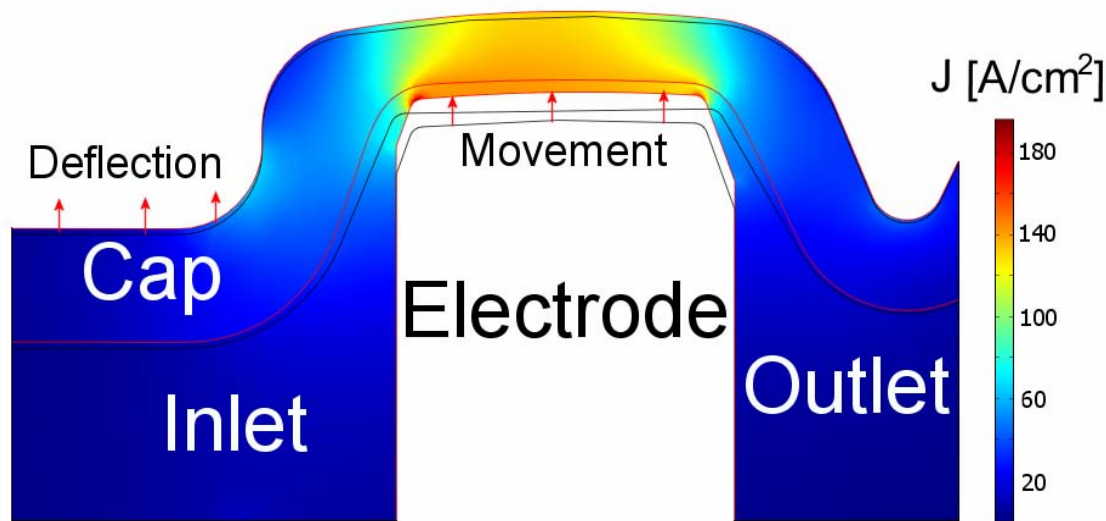
Reaction gas fraction [-]



Conductivity [m/s]








Simulation of material dissolution in practice



Philips Arcitec

Conclusions

Progress so far:

- Development cost is minimized 
- Process development time is decreased 
- Experiments run mainly virtually (are simulated) 
- Real experiment goes 'first time right' after simulation 
- Simulated process is robust and accuracy fulfills specification requirements 

Acknowledgement

We would like to thank:

- Dr. W. Hoogsteen for his contribution in the experimental research and consultancy
- P.J. Huizenga MSc for his research work on this subject during his traineeship

